

MATERIAL DECLARATION SHEET



Reliable Electronic Solutions

Material #	CD2320 Series	
Product Line	Integrated Passive & Active Devices	
Date	11/1/2005	
RoHS Compliant	Yes	

COMPONENT DETAILS

No.	Construction element	Material group	Material weight [g]	Materials	CAS if applicable	Average mass [%]	Sum [%]	Traces
1	FR-5	FR-5	0.0392	Glycidyl ether of bisphenol-A-Resin	28906-96-9	27.99	56.0	
				Bisphenol A-Resin	25085-75-0	25.14		
				Copper foil	7440-50-8	2.790		
2	GPRC	Chip	0.0056	Silicon	7440-21-3	2.280	7.95	
				Pb	7439-92-1	5.670		
3	Solder paste	Solder paste	0.0028	Sn	7440-31-5	3.840	4.00	
				Ag	7440-22-4	0.140		
				Cu	7440-50-8	0.020		
4	Plating	Pure tin	0.0014	Sn	7440-31-5	1.990	1.99	
5	Molding Component	Liquid epoxy	0.0210	Silica	7631-86-9	18.00	30.0	
				Epoxy resin	9003-36-5	9.000		
				Phenol resin	19438-60-9	3.000		
		Total weight	0.0700					

** Product is only available with lead free terminals.

Standard Part Number Example: CD2320-B11000

Note: Avg. mass and sum data is a % of the component weight.

It is the responsibility of the user to ensure that the latest revision is being accessed on the website.